



Product Change Notification

Change Notification #: 119036-00
Change Title: Select Intel® Enpirion® Power Solutions PowerSoC Devices, PCN 119036-00, Product Design, Inductor change
Date of Publication: April 19, 2022

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Last date to acknowledge receipt of this notification¹	July 22, 2022
Earliest change implementation	December 15, 2022

Note 1: J-STD-046, section 3.2.3.1b, stipulates that lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.

Description of Change to the Customer:

This is the same change described in PCN2214 issued on April 15, 2022.

Intel is notifying customers about a change of inductor in selected Intel Enpirion® PowerSoC Devices. There are no changes to form, fit and function. Qualification will be performed that includes reliability and device performance assessment.

Table 1: Change Details

	Change From	Change To
Supplier	Maglayers	FDK
Size Dimension	3.2 mm X 2.6 mm	3.2 mm X 2.5 mm
Thickness	Max 0.7mm	Max 0.75 mm
Inductor Value	1.1 uH	1.0 uH
DC Resistance	0.11	0.055
Rs@5Mhz	2	0.5 typ
Current	1.0A max	1.5A Sat
Material	Multi-layer Ferrite Chip Inductor	Multi-layer Power Inductor
SRF	70 Mhz	90Mhz typ
Inductance Tolerance	20%	25%
Termination Finish	Not specified (typ Ni/Sn)	Ag+ Ni/Sn

Note: The rest of the Bill of Material (BOM) remains the same

Reason for Change:

The supplier has issued a discontinuance notification of the existing inductor. The qualification of the new inductor will enable fulfillment of the last time buy orders of these selected Enpirion devices (Refer to related [PDN2133](#))

Qualification Plan:

Testing estimated to complete by August 2022.
 Vehicle device: EN5311QI.

Table 4: Reliability Test Plan

Test	Time point	Conditions	Standard	# of Lots
Temperature Cycle (TC) with Pre-conditioning (MSL3)	1000 Cycles	-55°C /125°C	JESD22-A104	3 lots/231 units
Device Validation Test	N/A	Vin=Vinmin to Vinmax Load= Loadmin to Loadmax Temp= -40C to +85 C	N/A	3 lots/30 units
Unbiased Highly Accelerated Stress Test (uHAST) with Pre-conditioning (MSL3)	96hrs	130°C / 85%RH	JESD22-A118	3 lots/231 units
High Temp Storage (HTS) with Pre-conditioning (MSL3)	1000hrs	150°C	JESD22-A103	3 lots/231 units

Customer Impact of Change and Recommended Action:

There is no impact to form, fit, function. Qualification will be performed for reliability and device performance assessment and to meet existing electrical and mechanical specifications.
 (See Qualification Plan Section, Table 4).

Customers are requested to:

1. Acknowledge receipt of this notification.
2. Review and inform us, at the earliest convenience, of any questions or concerns regarding this change.

Upon implementation, Intel will ship either pre-change or post-change materials.

For more information, please contact Sales in your region, or submit a Service Request at the [My Intel](#) support page.

Products Affected/Intel Ordering Codes:

Marketing Name	Stepping	MM#	Product Code	Spec Code
Intel® Enpirion® Power Solutions PowerSoC EP5382QI	A1	967972	EP5382QI	S R6P0
Intel® Enpirion® Power Solutions PowerSoC EP5352QI	A1	972052	EP5352QI	S R9QE
Intel® Enpirion® Power Solutions PowerSoC EN5311QI	A1	972585	EN5311QI	S RAPE
Intel® Enpirion® Power Solutions PowerSoC EP5362QI	A1	972756	EP5362QI	S RAUC
Intel® Enpirion® EN5311QI-C PowerSoC EN5311QI-C	A1	99AG0M	EN5311QI-C	S RKU3

PCN Revision History:**Date of Revision:**

April 19, 2022

Revision Number:

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Reason:

Originally Published PCN



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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

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